

[ABSTRACT]

A semiconductor processing sheet including a pressure-sensitive adhesive layer on a base material and having the following characteristics:

5 when the thickness of the aforementioned pressure-sensitive adhesive layer is 200 μm , the storage elastic modulus of the pressure-sensitive adhesive layer having a thickness of 200 μm at 0°C is equal to or less than 1,000 MPa; and

 when the semiconductor processing sheet is adhered to a mirror surface of a semiconductor wafer, the adhesive force of the pressure-sensitive adhesive layer with
10 respect to the mirror surface is equal to or less than 200 mN / 25 mm.